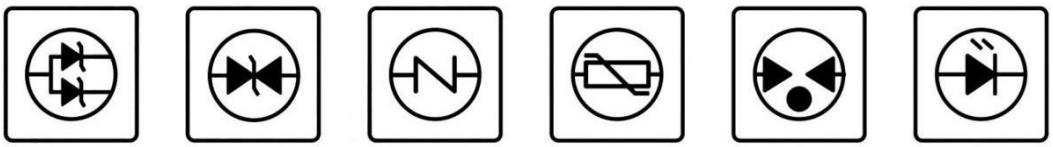
MSKSEMI 美森科
SEMICONDUCTOR



MURSXXXB-MS

Product specification

SURFACE MOUNT ULTRAFAST RECTIFIER

VOLTAGE:400V TO 600V

CURRENT: 3.0A

Features

- Ideally suited for use in very high frequency switching power
- supplies, inverters and as free wheeling diodes
- Ultrafast recovery time for high efficiency
- High surge capability
- High temperature soldering guaranteed
- 260℃/10sec/at terminals
- Glass passivated chip

Mechanical Data

- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Case: Molded with UL-94 class V-0 recognized Flame Retardant Epoxy
- Polarity: Color band denotes cathode end

Reference News

PACKAGE OUTLINE	Marking
	
SMB(DO-214AA)	*** Representative VRRM

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25℃, unless otherwise stated,for capacitive load, derate current by 20%)

	SYMBOL	MURS340B-MS	MURS360B-MS	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	400	600	V
Maximum RMS Voltage	Vrms	280	420	V
Maximum DC blocking Voltage	Vdc	400	600	V
Maximum Average Forward Rectified Current 3/8″lead length at T_L =90℃	If(av)	3.0		A
Peak Forward Surge Current 8.3ms single half sine- wave superimposed on rated load	Ifsm	125.0		A
Maximum Instantaneous Forward Voltage at rated forward current T_J =25℃	Vf	1.25		V
Maximum DC Reverse Current at rated DC blocking voltage Ta =25℃ Ta =125℃	Ir	10.0 50.0		μA
Maximum Reverse Recovery Time (Note1)	Trr	50		nS
Typical Junction Capacitance (Note 2)	Cj	50		pF
Typical Thermal Resistance, junction to lead	Rth(jl)	11		℃/W
Storage and Operating Junction Temperature	Tstg, Tj	-55 to +175		℃

Note:

1. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
2. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc

RATINGSANDCHARACTERISTICCURVES MURSXXXB-MS

Fig. 1 – Forward Current Derating Curve

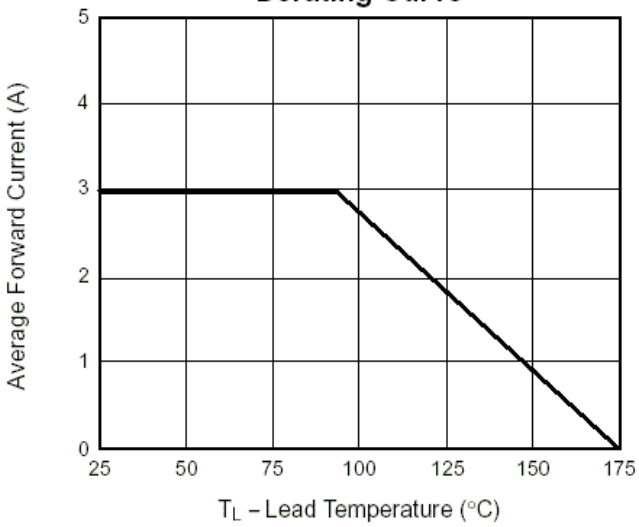


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

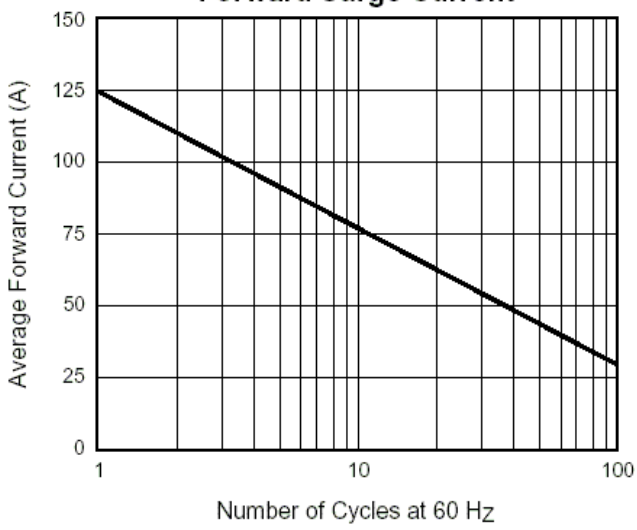


Fig. 3 – Typical Instantaneous Forward Characteristics

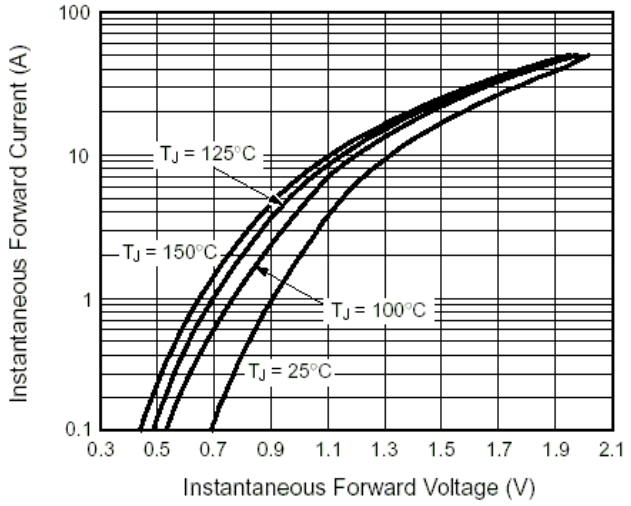


Fig. 4 – Typical Reverse Characteristics

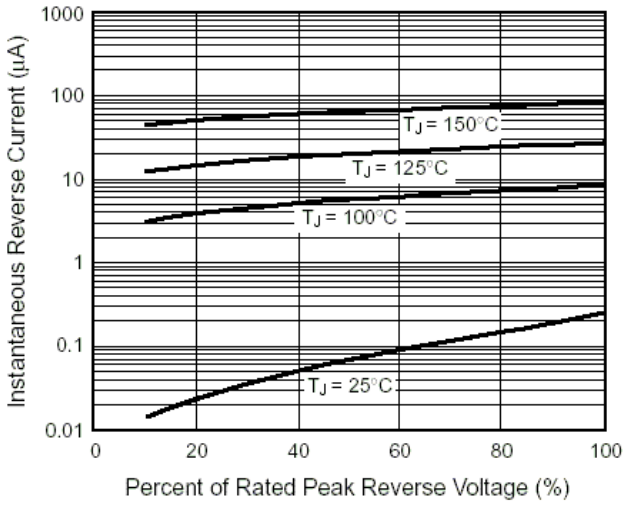
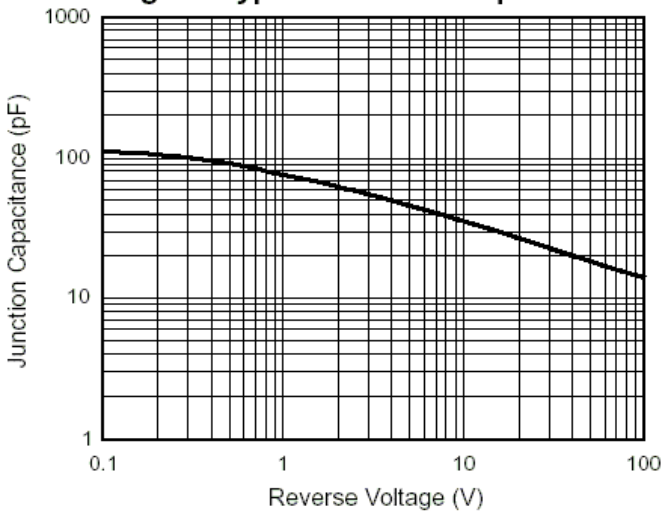
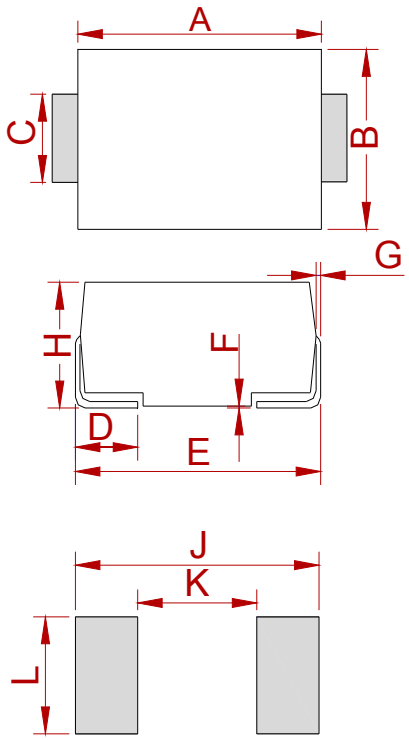


Fig. 5 – Typical Junction Capacitance



PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
MURSXXXB-MS	DO-214AA(SMB)	3000

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